Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

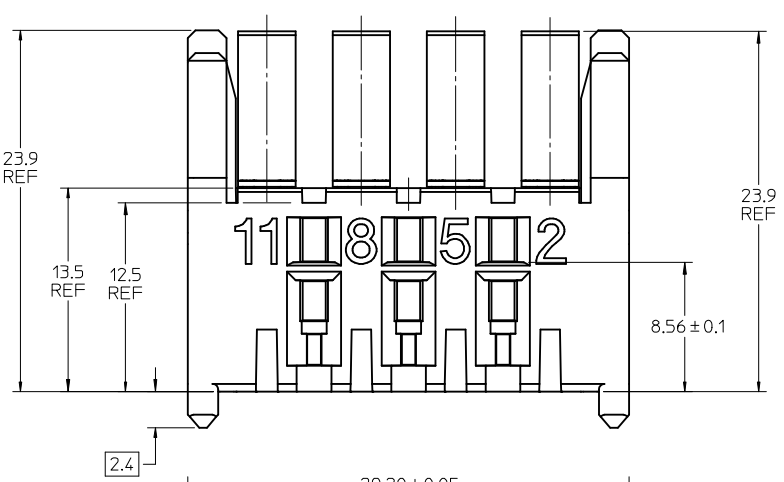
We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

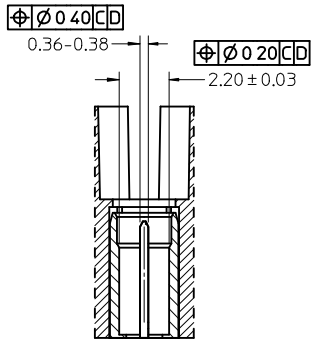
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

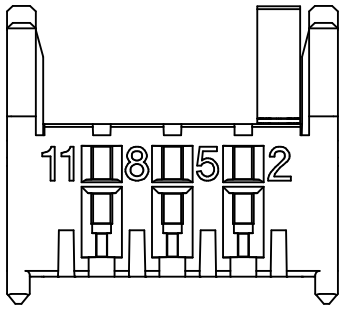
74642

MATERIAL NO.	TERMINAL LOADING BY POSITION
74642-0001	2, 5, 8, 11
74642-0002	2

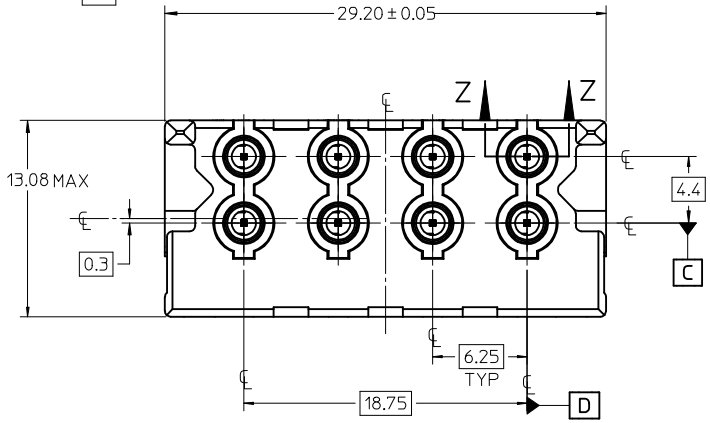


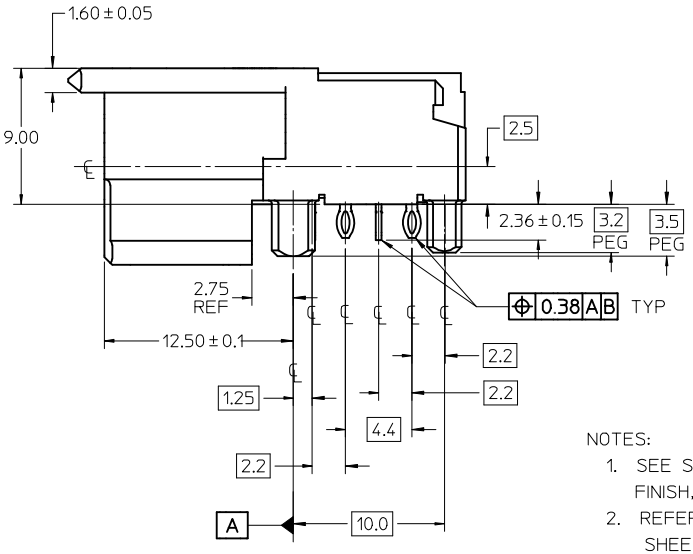


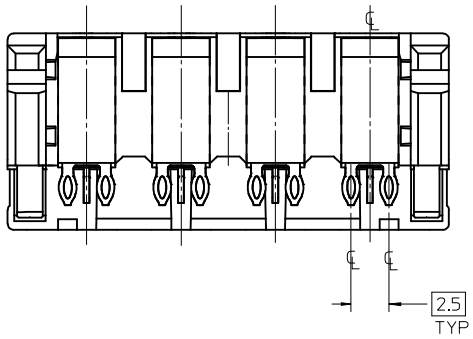
SECTION Z Z
SCALE 6:1

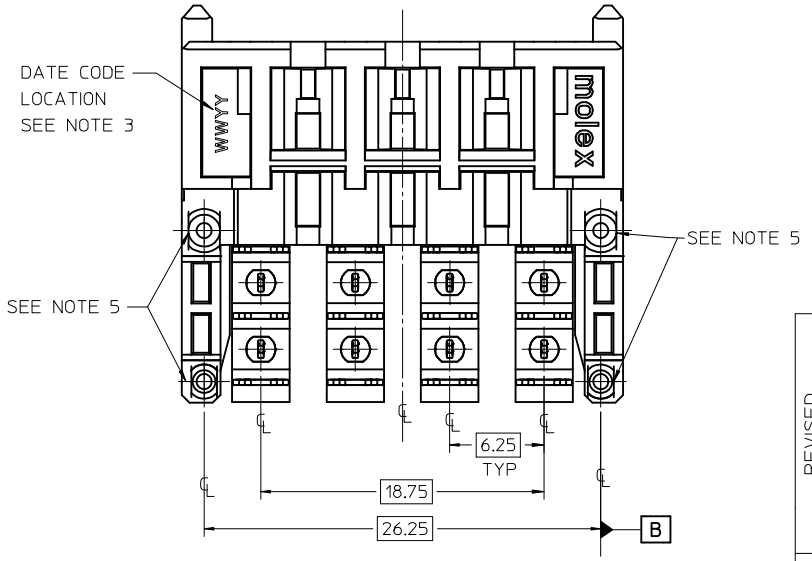


4 TERMINAL BAY ASSEMBLY
POSITION 2 LOADED ONLY
MATERIAL NO. 74642-0002









4 TERMINAL BAY ASSEMBLY
POSITION 2,5,8,11 SHOWN
MATERIAL NO. 74642-0001

NOTES:
1. SEE SHEET 4 FOR ALL NOTES PERTAINING TO MATERIAL, FINISH, PRODUCT SPECIDICATIONS AND PACKAGING.
2. REFER TO SHEET 2 FOR THE 3 TERMINAL BAY ASSEMBLY, SHEET 3 FOR THE 5 TERMINAL BAY ASSEMBLY AND SHEET 4 THEIR RELATED MATERIAL NUMBERS
3. DATE CODE TO BE LASER MARKED ON BOTTOM OF ASSEMBLY IN THE RECESSED POCKET LOCATION SHOWN.

REVISED
EC NO: UCP2009-0995
DRWN: JMENDOZA 2008/10/21
CH'KD:
APPR: JBINGHAM 2008/10/21
DESCRIPTION
REV
J2

QUALITY SYMBOLS
▼ - 0
▽ C - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 2 °		

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

SCALE 4:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY J. LONG DATE 01-02-08
CHECKED BY J. LONG DATE 01-02-08
APPROVED BY REGNIER DATE 01-03-20

TITLE
SALES DRAWING
FOR R/A GANGED RF
CONNECTOR ASSEMBLIES

MOLEX INCORPORATED

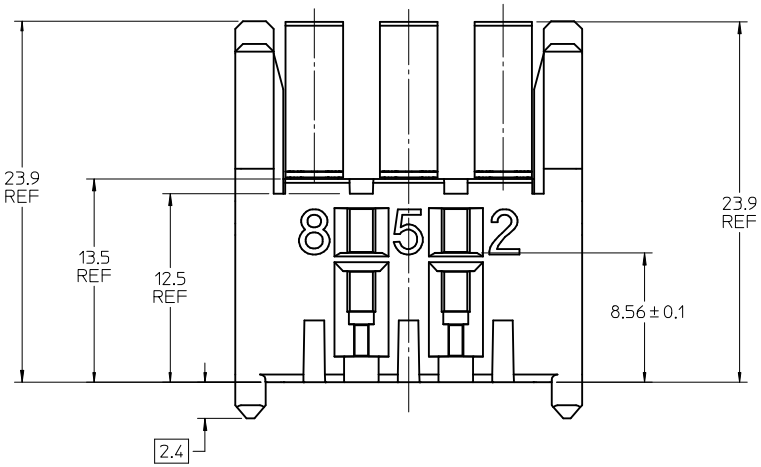
MATERIAL NO. SEE CHART | DOCUMENT NO. SD-74642-001 | SHEET NO. 1 OF 4

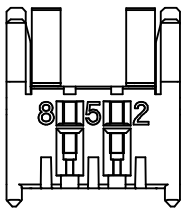
C

tb_frame_C-B1
rev. B1 2000/08/01

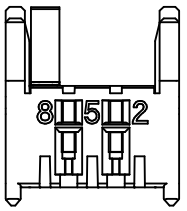
74642

MATERIAL NO.	TERMINAL LOADING BY POSITION
74642-1001	2, 5, 8
74642-1002	2, 8
74642-1003	2
74642-1004	8
74642-1005	5

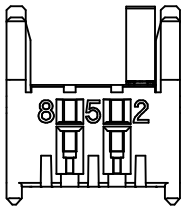




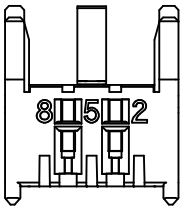
3 TERMINAL BAY ASSEMBLY
POSITIONS 2 & 8 LOADED
MATERIAL NO. 74642-1002



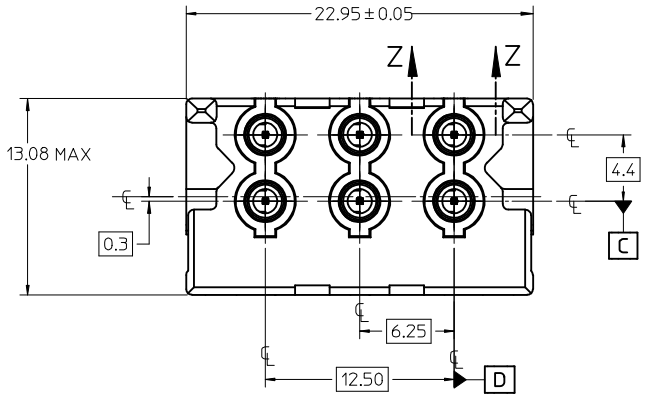
3 TERMINAL BAY ASSEMBLY
POSITION 8 LOADED
MATERIAL NO. 74642-1004

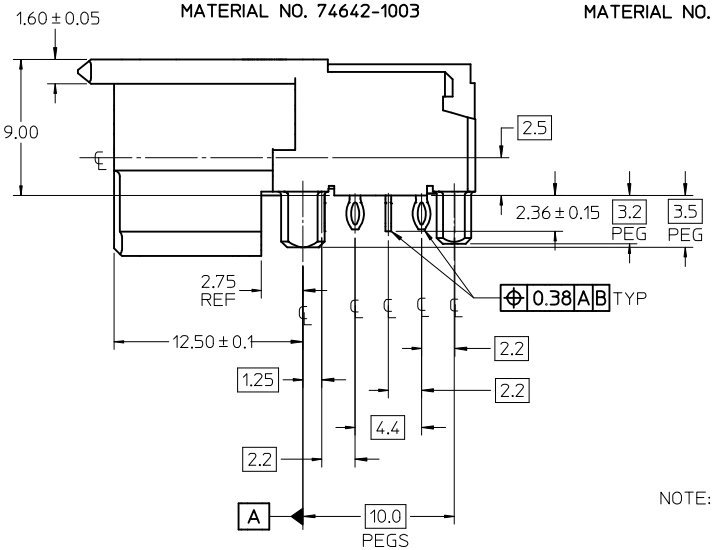


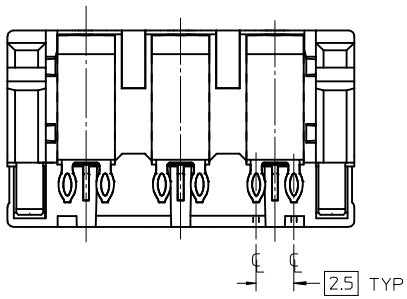
3 TERMINAL BAY ASSEMBLY
POSITION 2 LOADED
MATERIAL NO. 74642-1003

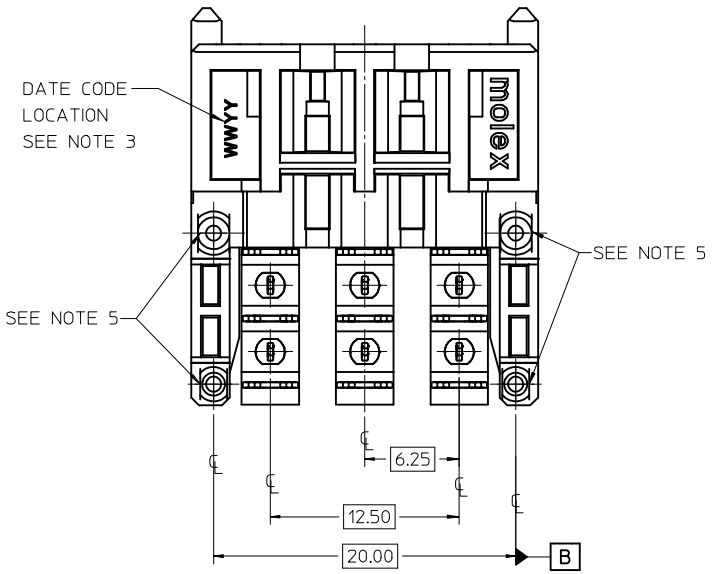


3 TERMINAL BAY ASSEMBLY
POSITION 5 LOADED
MATERIAL NO. 74642-1005









NOTE: REFER TO SHEET 1 FOR ALL DIMENSIONS, SECTION VIEW AND NOTES NOT SHOWN.

3 TERMINAL BAY ASSEMBLY
POSTION 2,5,8 SHOWN
MATERIAL NO. 74642-1001

SEE SHEET 1
EC NO: UCP2009-0995
DRWN: JMENDOZA 2008/10/21
CH'KD:
APPR: JBINGHAM 2008/10/21
DESCRIPTION
REV
J2

QUALITY SYMBOLS
▼ - 0
Ⓒ - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 2 °		

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

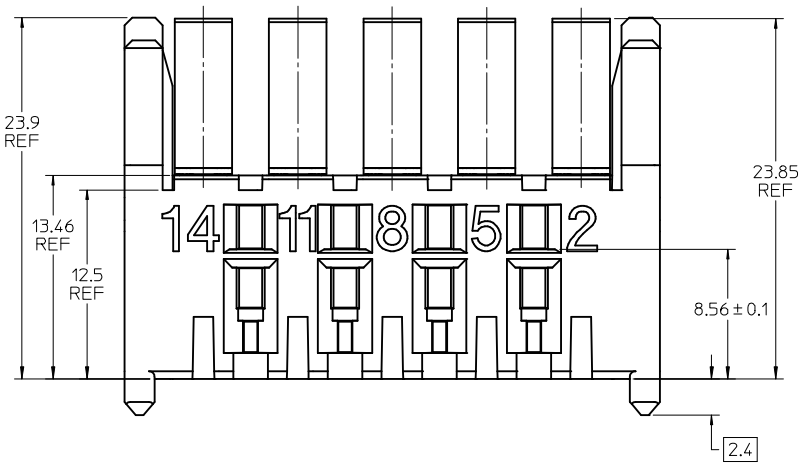
SCALE 4:1
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION
REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY J. LONG DATE 01-02-08
CHECKED BY J. LONG DATE 01-02-08
APPROVED BY REGNIER DATE 01-03-20
TITLE
SALES DRAWING
FOR R/A GANGED RF
CONNECTOR ASSEMBLIES
MOLEX INCORPORATED
MATERIAL NO. SEE CHART
DOCUMENT NO. SD-74642-001
SHEET NO. 2 OF 4

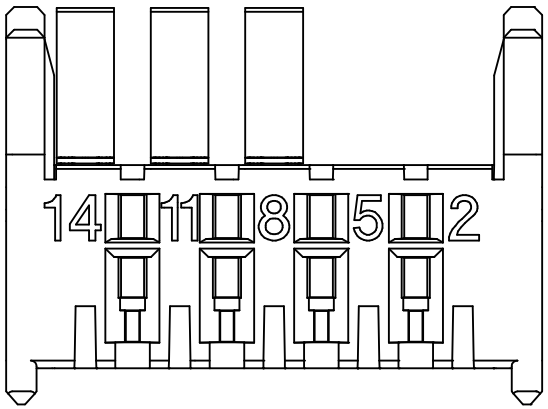
C

tb_frame_C-B1
rev. B1 2000/08/01

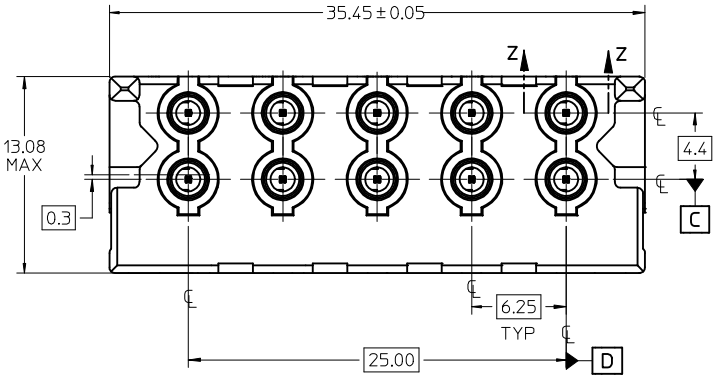
74642

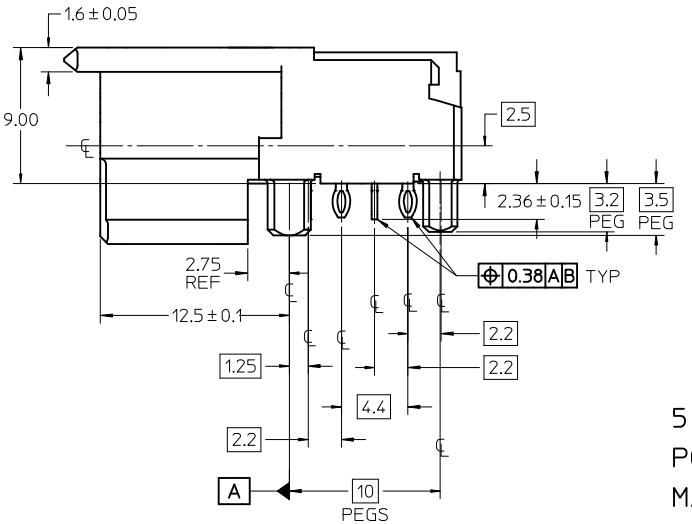
MATERIAL NO.	TERMINAL LOADING BY POSITION
74642-2001	2, 5, 8, 11, 14
74642-2002	8, 11, 14

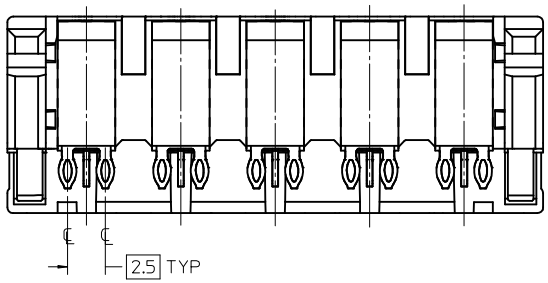


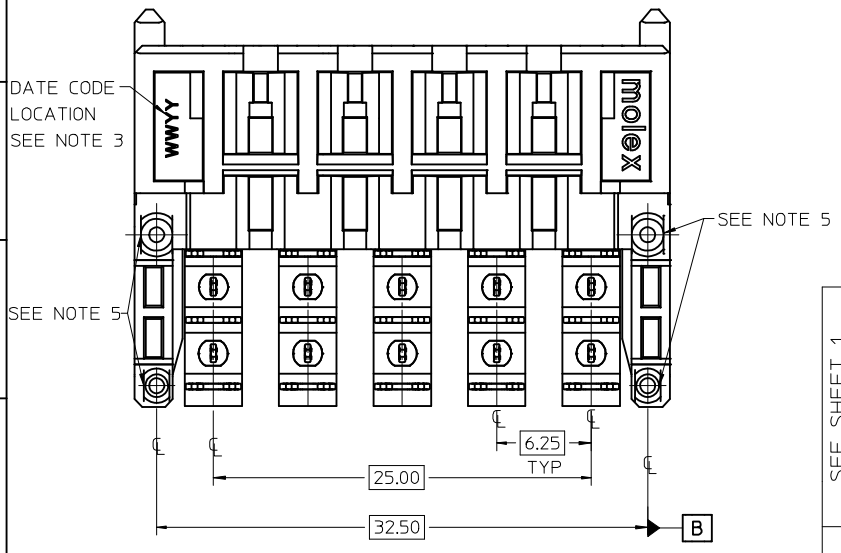


5 TERMINAL BAY ASSEMBLY
POSITION 8.11,14 SHOWN
MATERIAL NO. 74642-2002









5 TERMINAL BAY ASSEMBLY
POSITION 2.5.8.11,14 SHOWN
MATERIAL NO. 74642-2001

NOTE: REFER TO SHEET 1 FOR ALL DIMENSIONS, SECTION VIEW AND NOTES NOT SHOWN.

SEE SHEET 1
EC NO: UCP2009-0995
DRWN: JMENDOZA 2008/10/21
CH'KD: 2008/10/21
APPR: JBINGHAM 2008/10/21
DESCRIPTION
J2
REV

QUALITY SYMBOLS
▼ - 0
▽ - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 2 °		

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

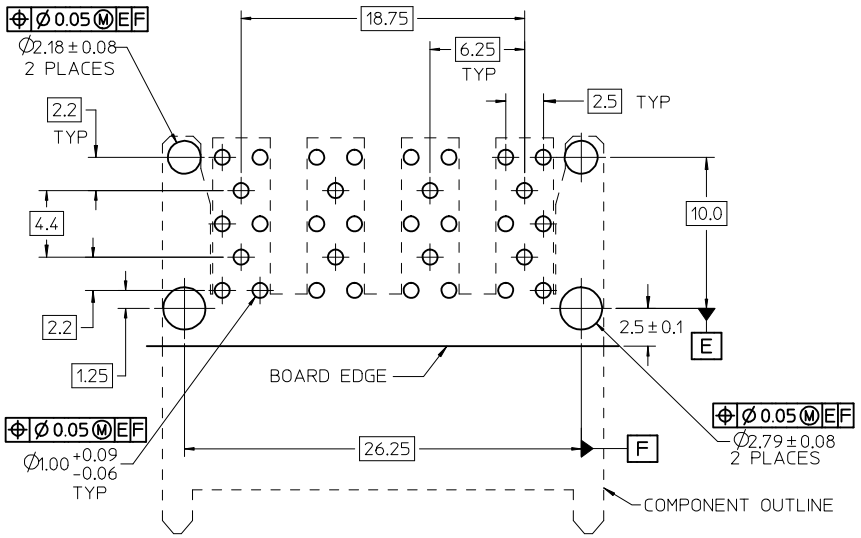
SCALE 4:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | REVISE ON CAD ONLY
DIMENSION STYLE MM ONLY
DRAWN BY J. LONG DATE 01-02-08
CHECKED BY J. LONG DATE 01-02-08
APPROVED BY REGNIER DATE 01-03-20

TITLE
SALES DRAWING
FOR R/A GANGED RF
CONNECTOR ASSEMBLIES

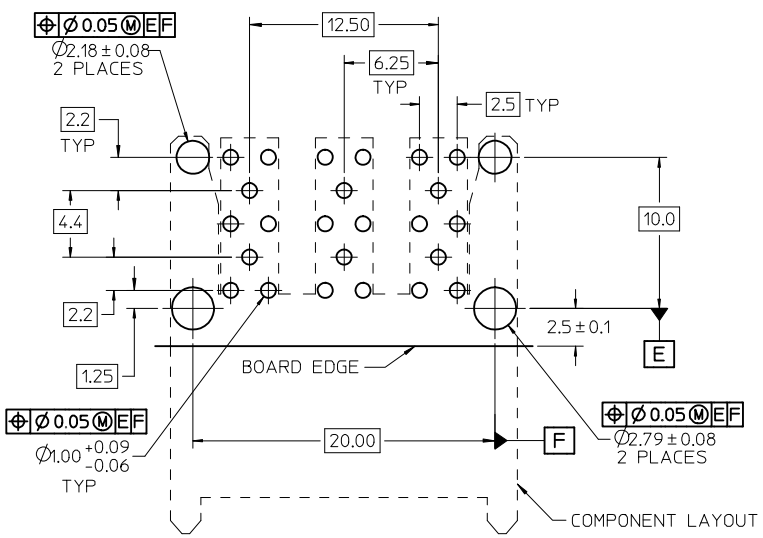
MOLEX INCORPORATED

MATERIAL NO. SEE CHART | DOCUMENT NO. SD-74642-001 | SHEET NO. 3 OF 4

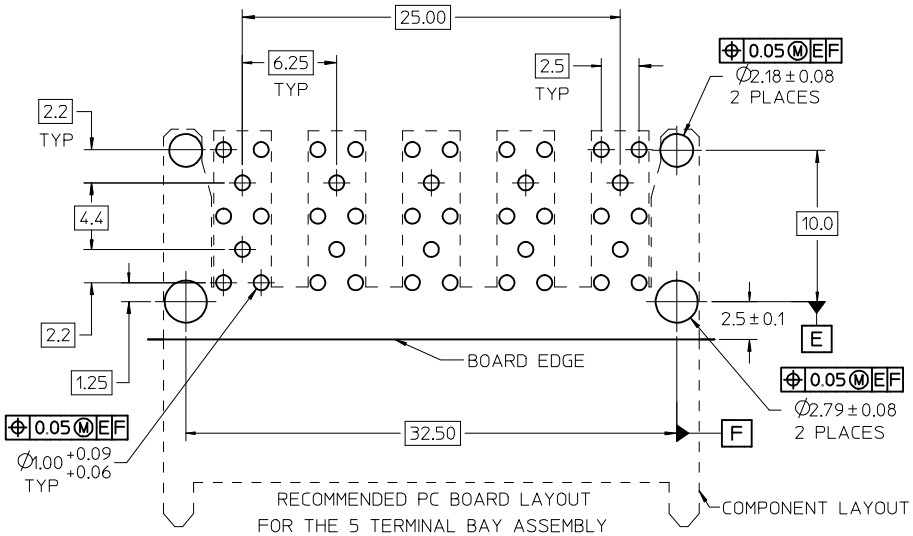
C



RECOMMENDED PC BOARD LAYOUT
FOR THE 4 TERMINAL BAY ASSEMBLY
COMPONENT SIDE OF BOARD
MINIMUM BOARD THICKNESS IS 2.36MM



RECOMMENDED PC BOARD LAYOUT
FOR THE 3 TERMINAL BAY ASSEMBLY
COMPONENT SIDE OF BOARD
MINIMUM BOARD THICKNESS IS 2.36MM



COMPONENT SIDE OF BOARD
MINIMUM BOARD THICKNESS IS 2.36MM

NOTES:

1. MATERIAL:
   - R/A HSG: GLASS FILLED LIQUID CRYSTAL POLYMER, COLOR: NATURAL
   - OVERMOLDED TERMINAL ASSEMBLY: GLASS FILLED HIGH TEMP PLASTIC
   - INSERT MOLDED TERMINAL: GLASS FILLED LIQUID CRYSTAL POLYMER, COLOR NATURAL
   - (ALL ABOVE HOUSINGS ARE UL 94V-0)
   - SLEEVE: BRASS
   - TERMINALS AND GROUNDS: TIN BRASS
   - DIE-CAST SHELLS: ZINC
2. FINISH:
   - TERMINALS:
     - SELECTIVE 0.76 MICRONS MIN.GOLD (Au) IN CONTACT AREA
     - SELECTIVE 0.88 MICRONS MIN.TIN (Sn) ALLOY IN THE PC TAIL AREA
     - BOTH OVER 1.27 MICRONS MIN. NICKEL (Ni) UNDERPLATE.
   - GROUNDS:
     - 0.88 MICRONS MIN. TIN (Sn) ALLOY OVERALL
     - OVER 1.27 MICRONS MIN. NICKEL (Ni) UNDERPLATE.
   - DIE-CAST SHIELDS:
     - 3.05 MICRONS MIN.BRIGHT TIN (Sn) ALLOY OVER
     - 1.27 MICRONS MIN. NICKEL (Ni) ALLOY OVER:
     - BOTH OVER 8.13 MICRONS MIN. COPPER (Cu) UNDERPLATE.
3. REFER TO PS-74854-001 PRODUCT SPEC FOR ALL ELECTRICAL, MECHANICAL AND ENVIROMENTAL SPECIFICATIONS.
4. REFER TO PK-74642-001 FOR ALL PACKAGING SPECIFICATIONS.
5. THESE PARTS CONFORM TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS B. EXCEPT ON THE PLASTIC PEGS, CLASS C

REV	DESCRIPTION	DRWN	CH'KD	APPR	DATE
J2	ADD NOTE 5 EC NO: UCP2009-0995	JMENDOZA		JBINGHAM	2008/10/21 2008/10/21 2008/10/21

QUALITY SYMBOLS
▼ - 0
▽ (C) - 0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 2 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

SCALE	4:1
DESIGN UNITS	METRIC
DIMENSION STYLE	MM ONLY
DRAWN BY	J. LONG
DATE	01-02-08
CHECKED BY	J. LONG
DATE	01-02-08
APPROVED BY	REGNIER
DATE	01-03-20

THIRD ANGLE PROJECTION
REVISE ON CAD ONLY

TITLE
SALES DRAWING
FOR R/A GANGED RF
CONNECTOR ASSEMBLIES

MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE CHARTS	SD-74642-001	4 OF 4

C